

3.5(H)mm, 2.0mm-travel Type SSSS2 Series

| Photo | Dimensions | Land Dimensions | Circuit Diagram | Packing Specifications |
 | Soldering Conditions |

PRINT

| | | |
|---------------------------------------|--|--------------------------|
| Part number | SSSS212301 | |
| Travel | 2mm | |
| Actuator directions | Horizontal | |
| Actuator length | 2mm | |
| Poles | 1 | |
| Positions | 3 | |
| Operating force | Refer to the dimensions. | |
| Changeover timing | Non shorting | |
| Soldering | Reflow | |
| Operating temperature range | -40°C to +85°C | |
| Rating (max.)/(min.) (Resistive load) | 0.3A 6V DC/50μA 3V DC | |
| Electrical performance | Contact resistance (Initial performance/After lifetime) | 70mΩ max./130mΩ max. |
| | Insulation resistance | 100MΩ min. 500V DC |
| | Voltage proof | 500V AC for 1 minute |
| Mechanical performance | Terminal strength | 3N for 1 minute |
| | Actuator strength | Operating direction 20N |
| | | Pulling direction 10N |
| Durability | Operating life without load | 10,000 cycles 100mΩ max. |
| | Operating life with load (at max. rated load) | 10,000 cycles 130mΩ max. |
| Environmental performance | Cold | -20°C 500h |
| | Dry heat | 85°C 500h |
| | Damp heat | 60°C, 90 to 95%RH 500h |

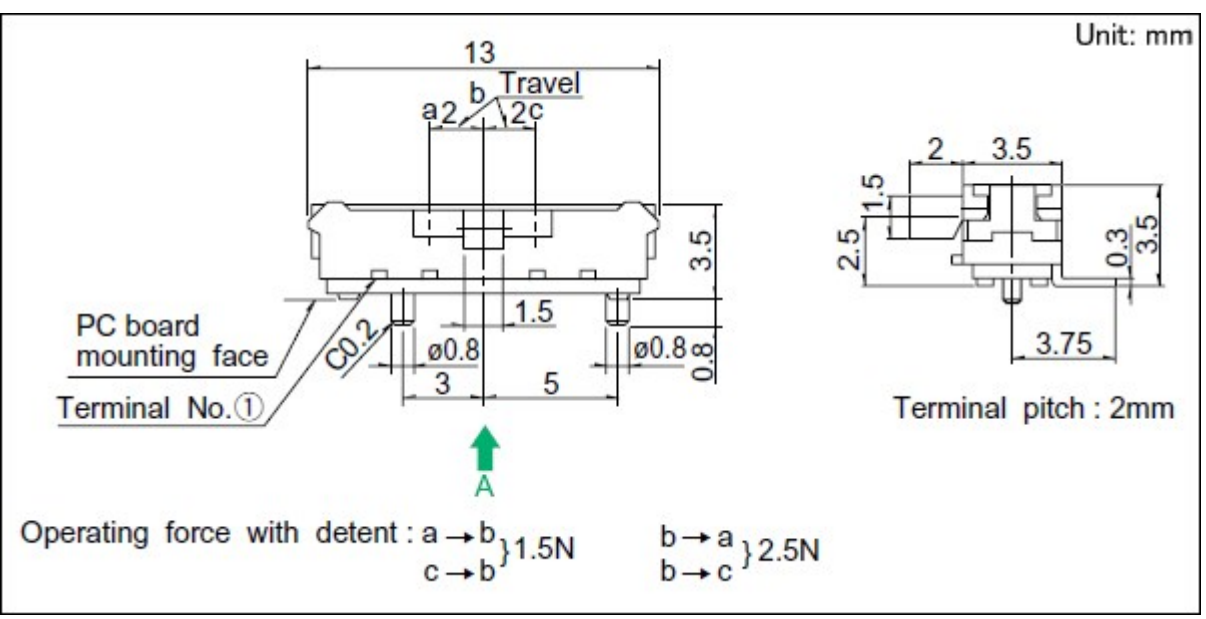
| | | |
|---------------------------|--------|-------|
| Minimum order unit (pcs.) | Japan | 1,400 |
| | Export | 5,600 |

- 3D CAD (STEP) [↓](#)
- Certificate of Compliance to RoHS regulations [↓](#)

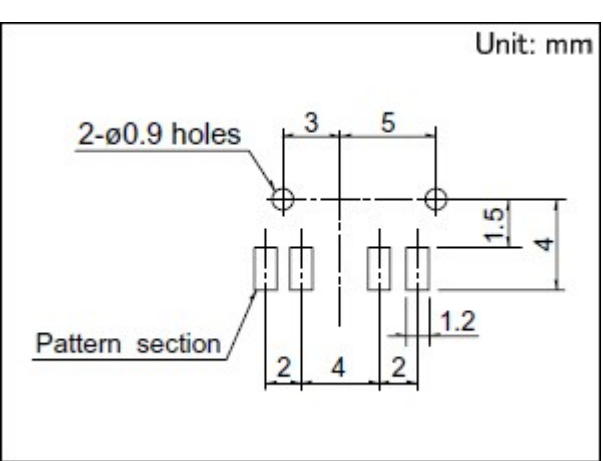
Photo



Dimensions

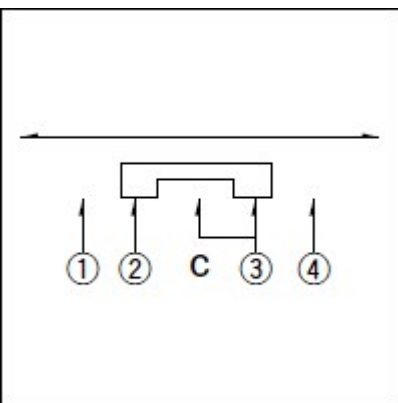


Land Dimensions



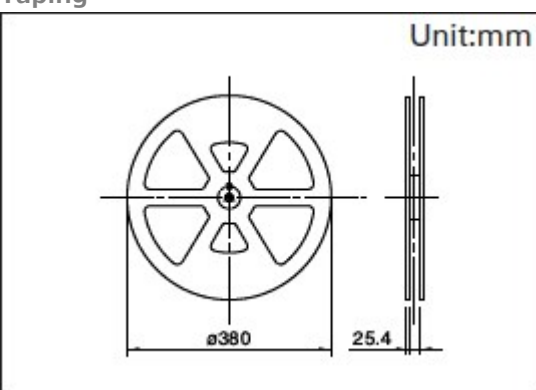
Viewed from direction A in the dimensions.

Circuit Diagram



Packing Specifications

Taping



Number of packages 1 reel 1,400
(pcs.)

1 case / Japan 2,800

1 case / export
packing 5,600

Tape width (mm) 24

Export package measurements (mm) 406×406×190

Soldering Conditions

Example of Reflow Soldering Condition

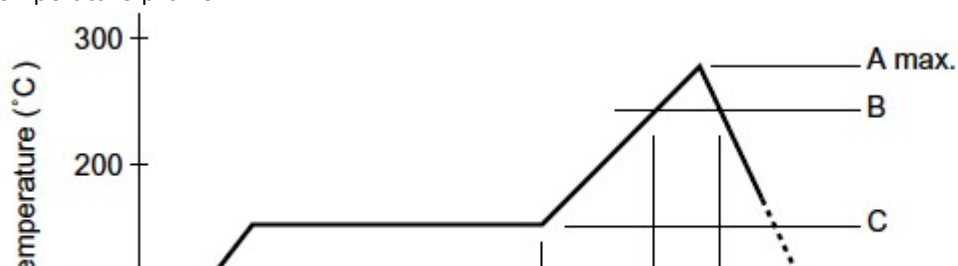
1. Heating method

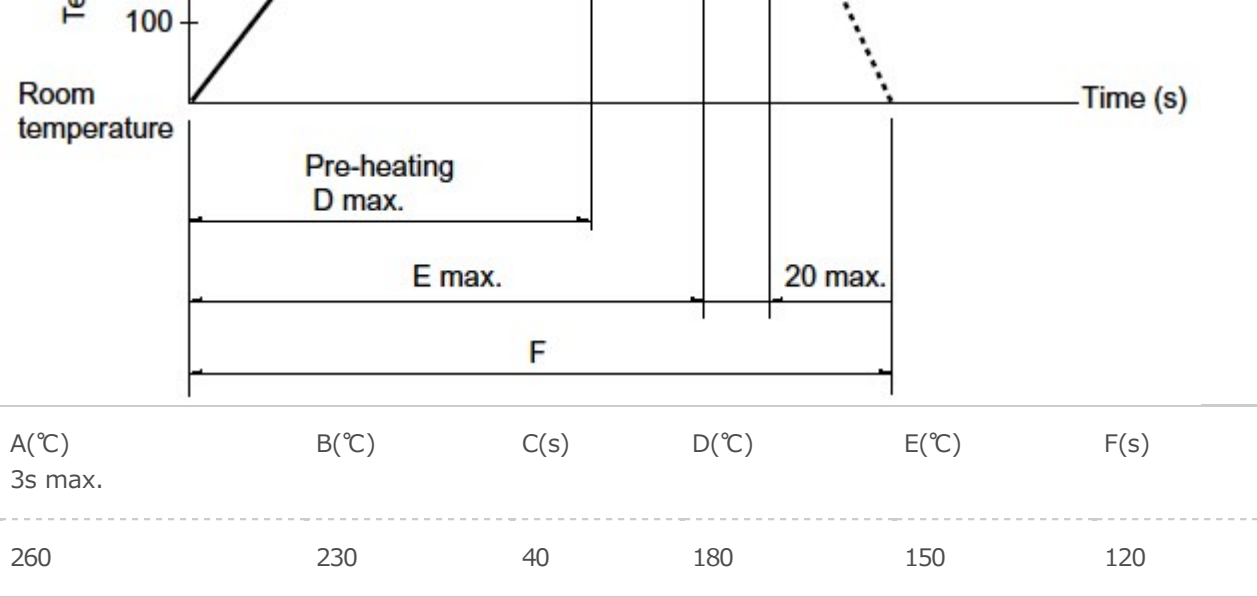
Double heating method with infrared heater.

2. Temperature measurement

Thermocouple 0.1 to 0.2 Φ CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

3. Temperature profile





(1) The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.

(2) Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

| | |
|-----------------------|----------|
| Soldering temperature | 350±10°C |
| Soldering time | 4s max. |

Notes are common to this series/models.

1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.
2. Please place purchase orders per minimum order unit (integer).
3. Products other than those listed in the above chart are also available. Please contact us for details.

Inquiries about Products

[Inquiry](#)